

IN THE CLAIMS:

Please note that all claims currently pending and under consideration in the referenced application are shown below. This listing of claims will replace all prior versions and listings of claims in the application.

Please amend claims 19, 21 through 23 and 25 through 34 as set forth below.

Listing of Claims:

1-18. (Canceled)

19. (Presently Amended) A method of fabricating a multi-die assembly, comprising:
providing a substrate including a plurality of conductors;
attaching at least one active face-down base die to said the substrate in electrical communication
with at least some of said the plurality of conductors;
providing a layer of conductive epoxy adhesive to a back side of the at least one base die;
placing a back side of at least one active face-up stack die on the layer of conductive epoxy
adhesive;
curing the layer of conductive epoxy adhesive and securing the back side of at least one stack die
to said the at least one base die;
providing a direct electrical path between said the at least one stack die and at least one of said
the plurality of conductors; and
electrically grounding said the at least one base die via said the layer of electrically conductive
epoxy adhesive and said the at least one stack die.

20. (Canceled)

21. (Presently Amended) The method of claim 19, further comprising:
securing at least one discrete component to at least one of said the at least one stack die, said the
the at least one base die, and said the substrate;

electrically connecting said the at least one discrete component to at least one of said stack die,
said the base die[[,]] and said the substrate; and
extending a die-to-component bond wire between said the at least one stack die and said the at
least one discrete component.

22. (Presently Amended) The method of claim 21, further comprising:
extending a component-to-substrate bond wire between said the at least one discrete component
and at least one of said the plurality of substrate conductors.

23. (Presently Amended) The method of claim 19, further comprising:
securing at least another stack die to said the assembly; and
electrically connecting said the at least another stack die and at least one of said the plurality of
substrate conductors.

24. (Canceled)

25. (Presently Amended) The method of claim 23, further comprising securing said the
at least another stack die to said the at least one stack die.

26. (Presently Amended) The method of claim 25, further comprising:
securing at least one discrete component to said the at least one stack die; and
extending a die-to-component bond wire between said the at least another stack die and said the
at least one discrete component.

27. (Presently Amended) The method of claim 25, further comprising:
securing at least one discrete component to said the at least one stack die; and
extending a component-to-substrate bond wire between said the at least one discrete component
and at least one of said the plurality of substrate conductors.

28. (Presently Amended) The method of claim 25, further comprising:
securing at least one discrete component to said the at least one base die; and
extending a die-to-component bond wire between said the at least another stack die and said the
at least one discrete component.

29. (Presently Amended) The method of claim 25, further comprising:
securing at least one discrete component to said the at least one base die; and
extending a component-to-substrate bond wire between said the at least one discrete component
and at least one of said the plurality of substrate conductors.

30. (Presently Amended) The method of claim 19, wherein the attaching at least one
active face-down base die includes attaching at least two active face-down base die to said the
substrate and electrically coupling each of said the at least two base die with at least one of said
the plurality of substrate conductors.

31. (Presently Amended) The method of claim 30, further comprising bridging said
the at least one stack die between said the at least two base die.

32. (Presently Amended) The method of claim 31, further comprising securing at
least another stack die over said the at least one stack die.

33. (Presently Amended) The method of claim 19, further comprising:
securing at least one discrete component to said the substrate; and
extending a die-to-component bond wire between said the at least one stack die and said the at
least one discrete component.

34. (Presently Amended) The method of claim 33, further comprising extending a
die-to-component bond wire between said the at least one discrete component and at least one of
said the plurality of substrate conductors.